FFSB2065B

Silicon Carbide Schottky Diode

650 V, 20 A

Description

Silicon Carbide (SiC) Schottky Diodes use a completely new technology that provides superior switching performance and higher reliability compared to Silicon. No reverse recovery current, temperature independent switching characteristics, and excellent thermal performance sets Silicon Carbide as the next generation of power semiconductor. System benefits include highest efficiency, faster operating frequency, increased power density, reduced EMI, and reduced system size & cost.

Features

- Max Junction Temperature 175°C
- Avalanche Rated 94 mJ
- High Surge Current Capacity
- Positive Temperature Coefficient
- Ease of Paralleling
- No Reverse Recovery/No Forward Recovery
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

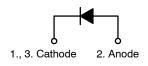
Applications

- General Purpose
- SMPS, Solar Inverter, UPS
- Power Switching Circuits



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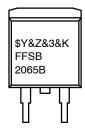


Schottky Diode



D²PAK-2 (TO-263, 2 LEAD) CASE 418BK

MARKING DIAGRAM



\$Y = ON Semiconductor Logo &Z = Assembly Plant Code

&3 = Numeric Date Code &K = Lot Code

FFSB2065B = Specific Device Code

ORDERING INFORMATION

See detailed ordering and shipping information on page 2 of this data sheet.

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ABSOLUTE MAXIMUM RATINGS (T_C = 25°C unless otherwise noted)

Symbol	Parameter		Value	Unit
V_{RRM}	Peak Repetitive Reverse Voltage		650	V
E _{AS}	Single Pulse Avalanche Energy (Note 1)		94	mJ
I _F	Continuous Rectified Forward Current @ T _C < 142°C		20	А
	Continuous Rectified Forward Current @ T _C < 135°C		22.8	
I _{F, Max}	Non-Repetitive Peak Forward Surge Current	T _C = 25°C, 10 μs	882	Α
		T _C = 150°C, 10 μs	798	
I _{F, SM}	Non-Repetitive Forward Surge Current T _C = 25°C	Half-Sine Pulse, t _p = 8.3 ms	84	Α
P _{tot}	Power Dissipation	T _C = 25°C	153	W
		T _C = 150°C	25.5	
T _J , T _{STG}	Operating Junction and Storage Temperature Range		-55 to +175	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected. 1. E_{AS} of 94 mJ is based on starting $T_J = 25^{\circ}C$, L = 0.5 mH, $I_{AS} = 19.4$ A, V = 50 V.

THERMAL CHARACTERISTICS

Symbol	Parameter	Ratings	Unit
$R_{ hetaJC}$	Thermal Resistance, Junction to Case, Max	0.98	°C/W

ELECTRICAL CHARACTERISTICS (T_C = 25°C unless otherwise noted)

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
V _F	Forward Voltage	I _F = 20 A, T _C = 25°C	-	1.38	1.7	V
		I _F = 20 A, T _C = 125°C	-	1.6	2.0	
		I _F = 20 A, T _C = 175°C	-	1.72	2.4	
I _R	Reverse Current	V _R = 650 V, T _C = 25°C	-	0.5	40	μΑ
		V _R = 650 V, T _C = 125°C	-	1	80	
		V _R = 650 V, T _C = 175°C	-	2	160	
Q _C	Total Capacitive Charge	V = 400 V	-	51	-	nC
C _{tot}	Total Capacitance	V _R = 1 V, f = 100 kHz	-	866	-	pF
		V _R = 300 V, f = 100 kHz	-	80	-	
		V _R = 600 V, f = 100 kHz	-	70	-	

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

ORDERING INFORMATION

Part Number	Top Marking	Package	Shipping [†]	
FFSB2065B	FFSB2065B	D ² PAK-2	800/Tape & Reel	

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

TYPICAL CHARACTERISTICS (T_J = 25°C unless otherwise noted)

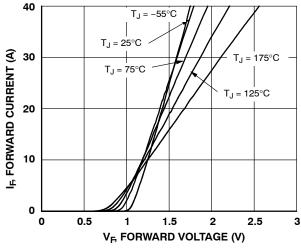


Figure 1. Forward Characteristics

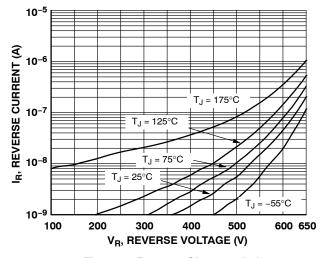


Figure 2. Reverse Characteristics

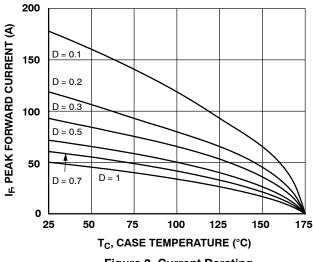


Figure 3. Current Derating

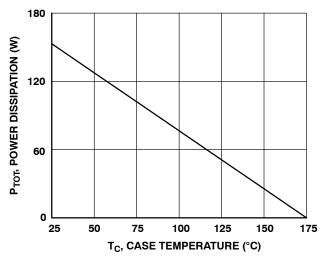


Figure 4. Power Derating

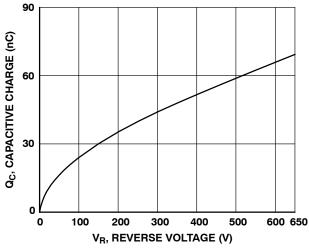


Figure 5. Capacitive Charge vs. Reverse Voltage

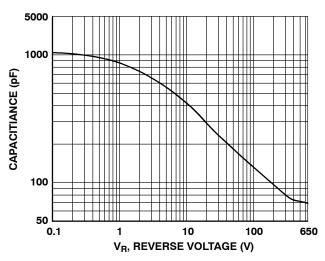


Figure 6. Capacitance vs. Reverse Voltage

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$\textbf{TYPICAL CHARACTERISTICS} \ (T_J = 25^{\circ}\text{C unless otherwise noted}) \ (\text{continued})$

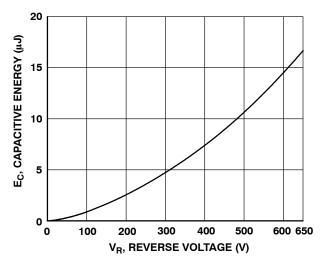


Figure 7. Capacitance Stored Energy

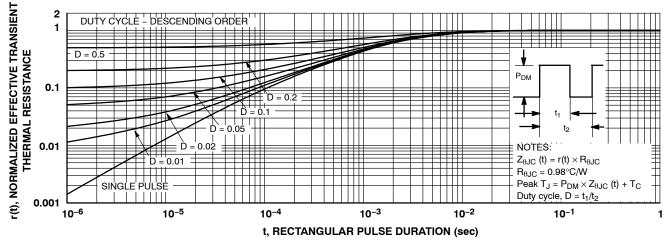
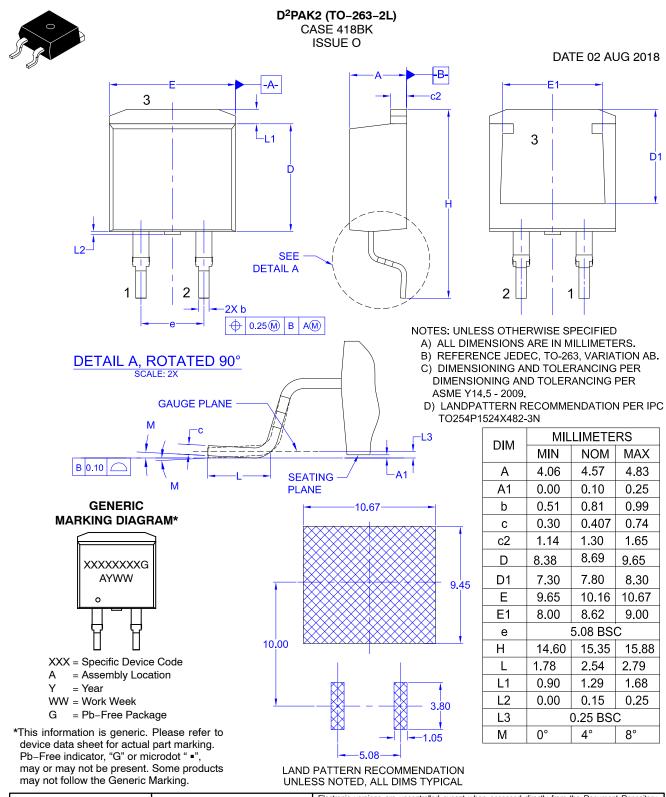


Figure 8. Junction-to-Case Transient Thermal Response Curve

L = 0.5 mH
R < 0.1 Ω
V_{DD} = 50 V
EAVL = 1/2LI2 [V_{R(AVL)} / (V_{R(AVL)} - V_{DD})]
Q1 = IGBT (BV_{CES} > DUT V_{R(AVL)})

V_{AVL}

Figure 9. Unclamped Inductive Switching Test Circuit & Waveform



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DESCRIPTION:	D ² PAK2 (TO-263-2L)		PAGE 1 OF 1	

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